



NOTES:

- PLATING THICKNESS:
ELECTRO Ni : 1.27~8.89 MICRON. (SOLDER PADS)
ELECTRO Au : 0.70~1.20 MICRON. (SOLDER PADS)
- CONNECTION:
(1-9-VCC), (2-XIN), (3-XOUT), (4-BN), (5-OUT+),
(6-10-GND-S/R-D/A), (7-OUT-), (8-RATE)
- CAMBER : 50.00 MICRON MAX.
- EXPOSURE OF METALLIZED PATTERN AND CERAMIC SURFACE OCCURRED BY MISALIGNMENT OF THE UPPER LAYER, SHALL BE ALLOWED.
- PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
- STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
- SEALING METHOD OF THIS PRODUCT SHALL BE SBAM WBLD.

TOLERANCE	REVISION	SBB ATTACHED EXCEPTIONS SHEET.			TITLE	
±% ±1% N.L.T.±0.13 ANGLES	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	5X7 PKG
	15 : 1	mm	3rd			
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	PART NO. S5070DCK4
90%MIN.A1203 (NA-311B BLACK)						REV. 0
						DWG NO. SHT/OF 1/6